

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



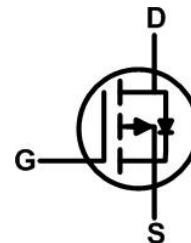
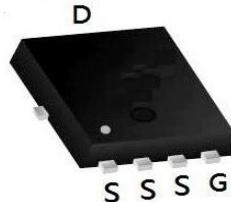
BVDSS	RDS(ON)	ID
-18V	3.6mΩ	-70A

PDFN5060-8L Pin Configuration

Description

The XR20P70F is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XR20P70F meet the RoHS and Green Product requirement with full function reliability approved.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-18	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-70	A
I _D @T _c =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-53	A
I _{DM}	Pulsed Drain Current ²	-280	A
P _D @T _c =25°C	Total Power Dissipation ³	62	W
P _D @T _c =70°C	Total Power Dissipation ³	35	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	3	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)		°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = -250\mu\text{A}$	-15	18	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -15\text{V}$, $V_{GS} = 0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = -250\mu\text{A}$	-0.35	-0.65	-1.0	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS} = -4.5\text{V}$, $I_D = -15\text{A}$	-	3.6	5.5	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}$, $I_D = -12\text{A}$	-	4.5	6.5	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -10\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$	-	6600	-	pF
C_{oss}	Output Capacitance		-	460	-	pF
C_{rss}	Reverse Transfer Capacitance		-	659	-	pF
Q_g	Total Gate Charge	$V_{DS} = -10\text{V}$, $I_D = -15\text{A}$, $V_{GS} = -4.5\text{V}$	-	76	-	nC
Q_{gs}	Gate-Source Charge		-	10	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	20	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}$, $I_D = -13\text{A}$, $R_{\text{GEN}} = 2.7\Omega$, $V_{GS} = -10\text{V}$	-	14	-	ns
t_r	Turn-on Rise Time		-	130	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	187	-	ns
t_f	Turn-off Fall Time		-	190	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-70	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-280	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}$, $I_s = -30\text{A}$	-	-	-1.2	V
trr	Reverse Recovery Time	$T_J = 25^\circ\text{C}$, $I_{SD} = -15\text{A}$, $V_{GS} = 0\text{V}$, $dI/dt = -100\text{A}/\mu\text{s}$	-	23	-	ns
Qrr	Reverse Recovery Charge		-	14	-	Nc

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J = 25^\circ\text{C}$, $V_{DD} = -10\text{V}$, $V_G = -10\text{V}$, $R_G = 5.9\Omega$, $L = 0.5\text{mh}$, $I_{AS} = -16\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

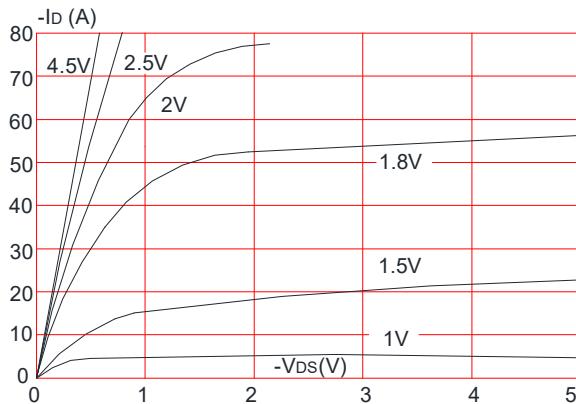


Figure 3: On-resistance vs. Drain Current

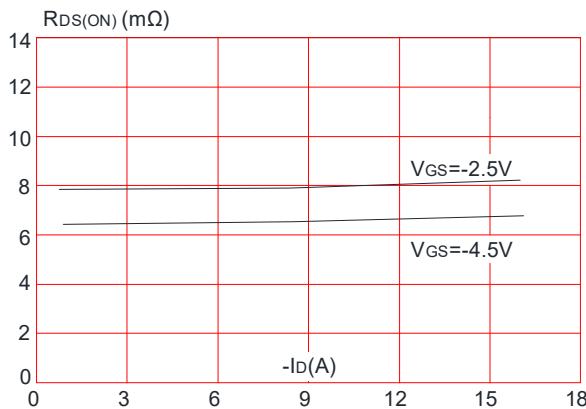


Figure 5: Gate Charge Characteristics

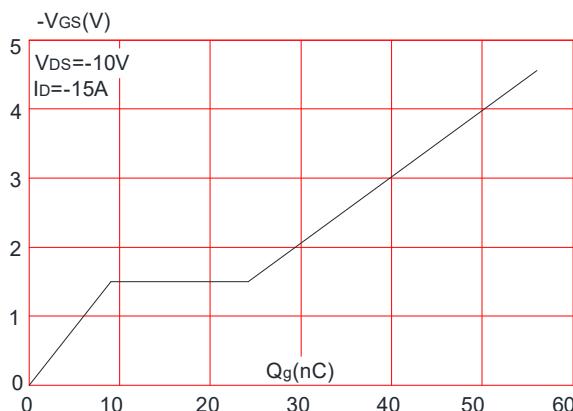


Figure 2: Typical Transfer Characteristics

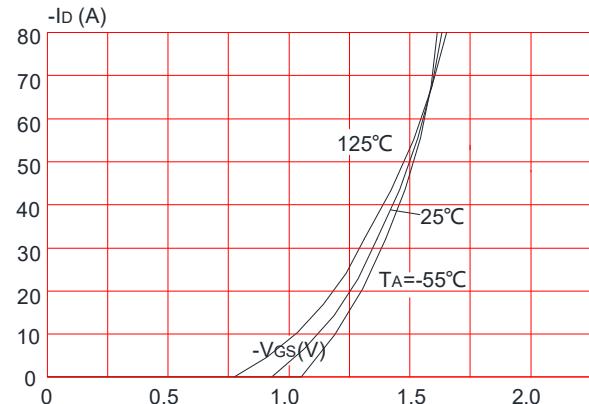


Figure 4: Body Diode Characteristics

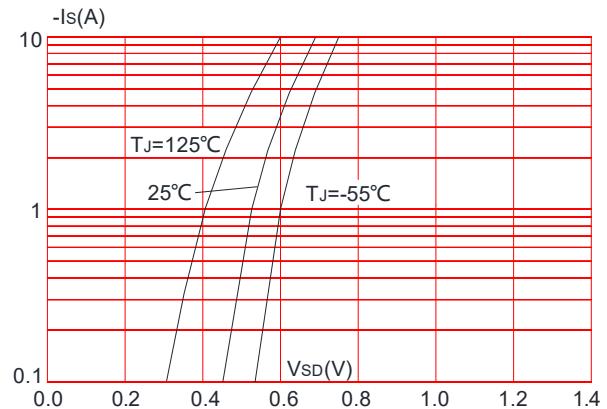
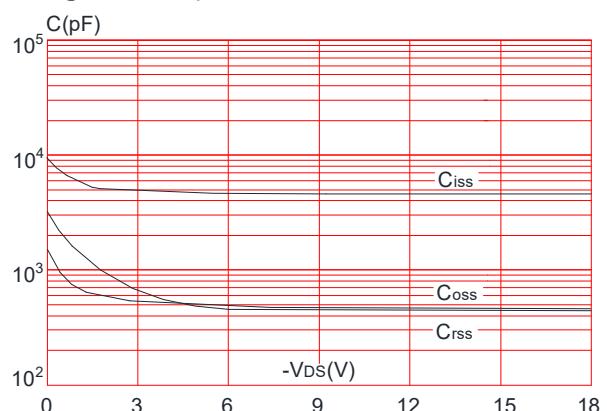


Figure 6: Capacitance Characteristics



P-Ch 18V Fast Switching MOSFETs

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

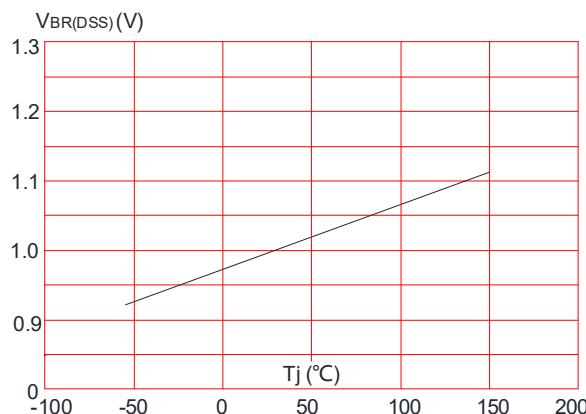


Figure 9: Maximum Safe Operating Area

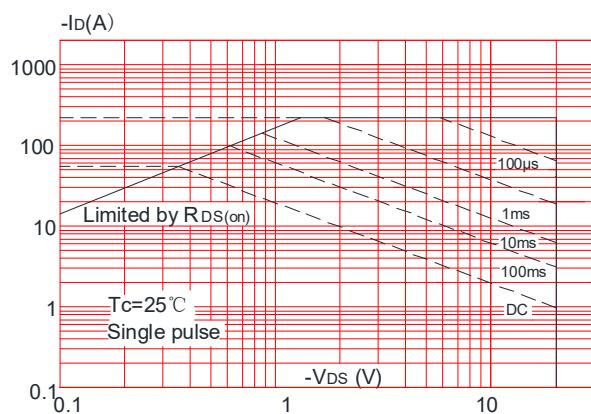


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

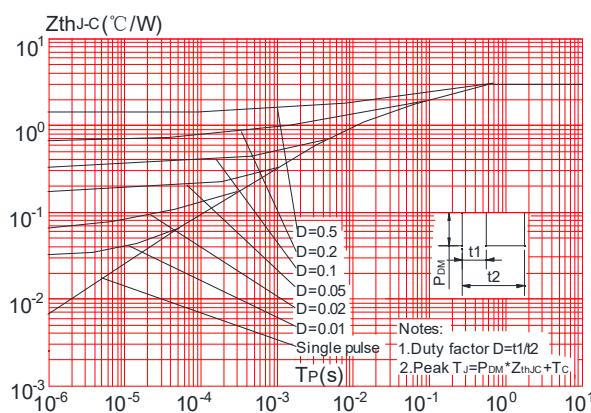


Figure 8: Normalized on Resistance vs. Junction Temperature

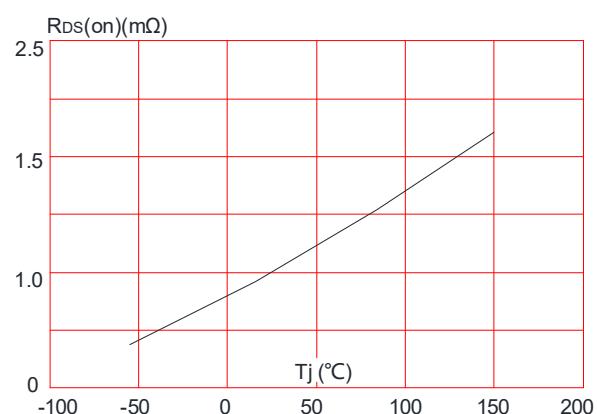
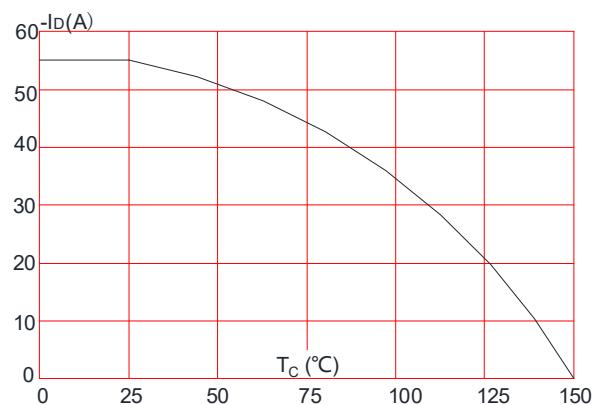
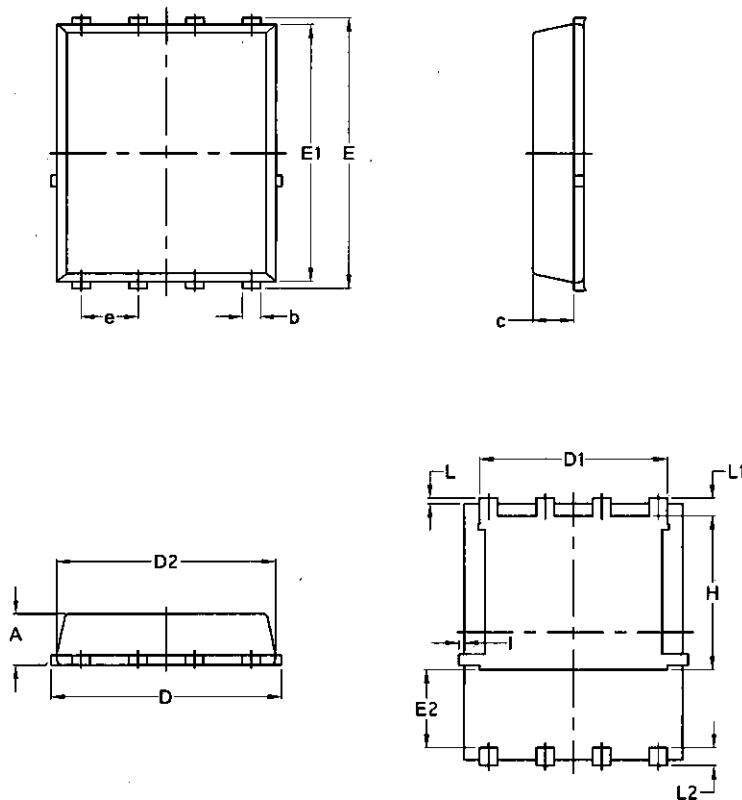


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070